

Subject 796F (746F)

March 19, 2018

SUMMARY OF TOPICS

The following topics were discussed at the meeting of the Standards Technical Panel for Flexible Materials Interconnect Constructions:

- 1. Update on standards projects for the Standard for Polymeric Materials – Flexible Dielectric Film Materials for Use in Printed-Wiring Boards and Flexible Materials Interconnect Constructions, UL 746F***
- 2. Update on standards projects for the Standard for Flexible Materials Interconnect Constructions, UL 796F***
- 3. Proposed revision to replace the second coverfilm reference with coverlay in Figure 2.5.1 of UL 796F***
- 4. Correction of references in 3.3.7 of UL 796F***
- 5. Clarification of dissimilar material evaluation for rigid flex constructions in UL 796F***
- 6. Proposed revision to the stabilization period requirements in UL 796F***
- 7. Additional references to tests using the oven conditioning in 5.1.5.4 of UL 796F***
- 8. Proposed revisions to the Dissimilar Dielectric Materials Thermal Cycling Test procedure in UL 796F***
- 9. Addition of requirement for sample stabilization period in UL 746F***
- 10. Strain relief fillets***
- 11. Overlap of material in transition zone***

A meeting of the Standards Technical Panel of UL for Flexible Materials Interconnect Constructions was held on March 1, 2018 at the San Diego Convention Center in San Diego, California. The purpose of the meeting was to discuss the status of current standards projects and to review proposed revisions to UL 796F and UL 746F.

The purpose of the STP meeting report is to briefly summarize discussions held during the meeting, and to document any resulting outcomes, including planned future action.

CALL TO ORDER, ANNOUNCEMENTS, INTRODUCTION OF MEMBERS, GUESTS, AND OBSERVERS

The STP Chair welcomed meeting attendees and asked everyone to introduce themselves. She explained the schedule for the day along with UL's Patent Policy and Antitrust Rules. UL's Patent Policy can be found at <http://ulstandards.ul.com/develop-standards/stps/ul-patent-policy/>. UL's Antitrust Rules can be found at <http://ulstandards.ul.com/develop-standards/stps/ul-antitrust-rules/>. The Project Manager circulated an attendance list. The meeting attendees were notified that if they experience any problems with UL's Collaborative Standards Development System (CSDS) they should contact the STP Project Manager for assistance.

The current balance of the STP is shown in the following table:

Interest Category	Number of Members	Interest Category	Number of Members
Producers	6 (29%)	Government	1 (5%)
Testing & Standards Organizations	6 (29%)	Consumer	0 (0%)
Supply Chain	3 (14%)	General Interest	5 (24%)
AHJs	0 (0%)	Commercial/Industrial User	0 (0%)

FUTURE MEETING SCHEDULE

It is anticipated that the next STP meeting will be scheduled for Thursday, January 31, 2019 at the San Diego Convention Center in conjunction with the IPC Expo.

DISCUSSION OF PROPOSALS AND AGENDA TOPICS

1. Update on standards projects for the Standard for Polymeric Materials – Flexible Dielectric Film Materials for Use in Printed-Wiring Boards and Flexible Materials Interconnect Constructions, UL 746F

DISCUSSION

There are currently no standard projects opened for the Standard for Polymeric Materials – Flexible Dielectric Film Materials for Use in Printed-Wiring Boards and Flexible Materials Interconnect Constructions, UL 746F.

2. Update on standards projects for the Standard for Flexible Materials Interconnect Constructions, UL 796F

DISCUSSION

There are currently no standard projects opened for the Standard for Flexible Materials Interconnect Constructions, UL 796F.